## **Integration Platforms Towards Wafer Scale**

- Alic Chen, WeiWah Chan , Thomas Devloo, Giovanni Gonzales, Christine Ho, Mervin John, Jay Kaist, Deepa Maden, Michael Mark, Lindsay Miller, Peter Minor, Christopher Sherman, Mike Seidel, Peter So, Joe Wang, Andrew Waterbury, Lee Weinstein, Richard Xu, Fred Burghardt, Dr. Igor Paprotny, Dr. Yiping Zhu, Dr. Eli Leland, Prof. Jan Rabaey, Prof. Jim Evans, Prof. Dick White, and Prof. Paul Wright
- Electrical Current and Voltage sensing
  - Integration with TI Motes
- Fluid Flow Devices for HVAC systems
  - Integration with electronics
- Vibration based Devices for general equipment
  - Integration with low power radios
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# Electrical Current and Voltage sensing

The average electric power consumption of Cory Hall is IMW. Presently the power entering that building is metered only manually at the primary terminals of its distribution step-down transformer.

➢ We are designing and testing mesoscale and MEMS-based electric sensors for real-time current, voltage and power monitoring. Our sensor technology will allow us to monitor current and voltage through existing banks of standard circuit breakers.

Automated monitoring will be achieved using commercially available equipments, such as TI motes.



EECS Building--Cory Hall, built in 1953



# Sensing Technology

	Current sensor	Voltage sensor (under development)		
Structure	Piezoelectric cantilever with permanent magnets mounted on its tip	A MEMS cantilever connected to a broad capacitive pickup		
Physics	Permanent magnets couples with alternating magnetic field due to breaker current. The vibration of piezoelectric cantilever produces a electric signal that is proportional to the breaker current.	Micromechanical motion induced by the variation of electric field provides a measure of the electric potential.		
Design & Prototype		ΠΟυμm		

# Wireless Communication

- I. **RFID** technologies
- 2. Texas Instruments, eZ430-RF2500 radio motes



## Future work

 $\succ$  Test MEMS-scale current sensors to determine sensitivity, linearity, and transient response.

Construct and test the sealed energy-scavenger (shown below) module to determine its suitability for powering wireless units AC magnetic and/or electric fields.

Study sensor designs for capturing and reporting features such as power-line transients and load signatures.

Finalize voltage sensor design.



# Cylindrical Obstacle Flow Scavenger

We have had the most success with a rectangular flat plate in the wake of a cylindrical obstacle.





The Reynolds numbers associated with the flows in the pipe are in the turbulent range. This presents many challenges.

Design parameters for this setup include:

- Cylinder Diameter
- Fin material
- Fin length and width
- Separation distance between cylinder and fin

# Natural Frequency of Bender & Fin

We have measured the natural frequencies of different fins using a shaker table setup. Varying the length and width of the fin gives good control over the bender's natural frequency.

Using fin materials with different densities also affects natural frequency. Balsa wood is the best material for our needs that we have tested so far.

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# Vortex Shedding Frequency

Certain obstructions in flows, such as cylinders, have periodic vortex shedding.

We have used COMSOL as well as Strouhal number relationships from the literature to model the shedding frequency from the cylinder.

$$f = \frac{St * v}{D}$$
$$St = St^* + \frac{m}{\sqrt{Re}}$$

For Re > 5000, St\* = 0.1776 m = 2.2023



Shedding Frequency vs. Air Speed for Various Cylinder Diameters



### Damped Oscillator Response

The bender and fin can be modeled as a damped oscillator. Because of the way damped oscillators respond to periodic inputs, matching frequencies is essential for high performance.

The relationship between input force and power out (transmissibility) is based on the ratio of input frequency to resonance frequency. This is calculated through the equation below and shown in the figure to the right for various damping coefficients.





## Performance

Successful trials have shown power outputs of 1 mW and higher for certain configurations.

For results shown: Fin dimensions: 7.5 cm wide x 7 cm long Cylinder Diameter: 2.5 cm Optimum Load Resistance: 194 kOhm



Load Resistance (kOhm)

Avg. Air Speed (m/s)

Flow Speed	lm/s	1.5 m/s	2 m/s	2.5 m/s	3 m/s	3.5 m/s	4 m/s	4.5 m/s	5 m/s
RMS Power	2 uW	4 u₩	3∣ uW	282 uW	40 uW	619 uW	298 uW	205 uW	181 uW

# Piezoelectric Bender Geometry

### **Motivation for Trapezoid**

• Triangles are the most optimal at uniformly distributing stress, but difficult to build and implement.

• Using Finite Element Analysis (FEA) methods, a trapezoid geometry was designed to concentrate stress at the base of piezoelectric harvester.

### **Choosing an Operating Frequency**

**Design Parameters** 

- a, Input acceleration
- f<sub>op</sub>, Desired operating frequency
- M, Added end mass

#### For maximum power output:

 $f_{op} = f_{resonance}$ 

• 
$$f_{resonance} = (k/m)^{1/2}$$

Tune bender's resonant frequency by adding mass at the tip of trapezoid. For  $f_{op} = 100$  Hz use M = 7.7 g For  $f_{op} = 120$  Hz use M = 4.9 g





End mass realized as a block of Tungsten glued to bender tip.  $\rho_{tungsten} = 19.3 \text{ g/cc}$ 



### **Optimum Load Resistance**

# Power Performance



Device performance is tested on a shaker table equipped with an accelerometer to produce the following plots.

The optimum load resistance was found to be:  $R_{optimum} = 105k\Omega$ 

Given a sinusoidal input and constant acceleration the following power out for the desired operating conditions are:

For a = 0.05gP =  $28\mu W$ For a = 1gP = 10.4m W



#### **Power-Frequency Response**







Given a 10 second charge time and two packets per Tx event, duty cycle ("on" time / "off" time) is about 0.2%

# Here is the chip with printed storage:

This is the first phase of work to integrate energy harvester with energy storage





Alic and Lindsay successfully printed mass on 6 released beams in order to modify the resonance frequency. There were no "casualties".



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### Advantages with printing

- Fast
- Easily scalable
- Done <u>after completion</u> of all microfabrication steps including release
- Done in ambient conditions
- Non-destructive

### Future possibilities

- Print the capacitor and battery <u>as the mass</u> of the beam
- Improve power density by using printed mass to utilize 3D space instead of needing to expand in the area of the Si wafer

### Towards a System on a Chip

